REMARKS

Applicant respectfully requests that the foregoing amendments be made prior to examination of the present application. New matter has not been added.

Respectfully submitted,

Date April 12, 2002

By _____

William T. Ellis
Attorney for Applicant
Registration No. 26,874

FOLEY & LARDNER
Customer Number: 22428
22428
PATENT TRADEMARK OFFICE
Telephone: (202) 672-5485
Facsimile: (202) 672-5399

Version With Markings to Show Changes Made

Marked up rewritten claims:

1. (Amended) A conductor track supporting layer [(1)] for laminating inside a chip card [(8)] comprising at least one conductor track [(2)] which is applied to a conductor track supporting layer [(1)] by an application method, preferably a screen printing method, and consists of a conductive paste or high-viscosity liquid, and comprising connecting areas [(3)] which are connected to the conductor track [(2)], characterized in that the conductor track supporting layer [(1)] has in the region of the connecting areas [(3)] indentations [(4a, 4b, 4c)] which are filled with the paste or the high-viscosity liquid during the application operation.

2. (Amended) The conductor track supporting layer as claimed in claim 1, [characterized in that] wherein the indentations [(4a, 4b, 4c)] are made as through-holes [(6)] with an opening [(7)] on the rear side [(9)] of the conductor track supporting layer, lying opposite the conductor track [(2)] of the supporting layer [(1)].

3. (Amended) The conductor track supporting layer as claimed in claim 2, [characterized in that] wherein it is provided on the rear side [(9)] with a protective film [(10)].

4. (Amended) The conductor track supporting layer as claimed in [one of claims 1 to 3, characterized in that] claim 1, wherein the conductor track [(2)] has the form and function of a coil.

5. (Amended) The conductor track supporting layer as claimed in [one of claims 1 to 4, characterized in that] claim 1, wherein the screen printing paste [(5)] has a silver particle content of from 70 to 80% percent by volume.

6. (Amended) The conductor track supporting layer as claimed in claim 5, [characterized in that] wherein the grain size of the silver particles is greater than 45 µm.

7. (Amended) The conductor track supporting layer as claimed in [one of claims 1 to 6, characterized in that] claim 1, wherein a plurality of sublayers [(18, 19, 20)] provided with through-holes [(21)] are stacked exactly in position one on top of the other and bonded to one another to form a common conductor track supporting layer [(1)], indentations [(4a, 4b, 4c)] of different depths being formed by making the positions of the through-holes [(21)] in the sublayers [(18, 19, 20)] coincide.

8. (Amended) A chip card with a chip module [(11)], arranged in a recess [(12)] of the chip card body [(16)], and/or further electronic components, with a conductor track supporting layer [(1)], to which at least conductor tracks [(2) consisting of] comprising a screen printing paste and connecting areas [(3)] connected to the conductor track [(2)] have been applied by a screen printing method, characterized in that the conductor track supporting layer [(1)] has in the region of the connecting areas [(3)] indentations [(4)] filled with screen printing paste, in that the recess [(12)] for the chip module [(11)] and/or further electronic components is arranged on the side of the conductor track supporting layer [(1)] not coated with the conductor track [(2)] and in that the recess [(12)] has such a depth that the bottom region reaches so far into the conductor track supporting layer [(1)] that the indentations [(4a, 4b, 4c)] filled with screen printing paste of the conductor track supporting layer [(1)] are exposed.

9. (Amended) A method for producing a chip card, comprising a multilayer plastic card body [(16)], at least one electronic component, preferably a chip module [(11)], arranged in a recess [(12)] of the plastic card body [(16)], in which

at least one conductor track supporting layer [(1)], at least two covering layers [(14, 15)] covering the conductor track supporting layer [(1)] on both flat sides are arranged exactly in position one on top of the other,

the card layers [(1, 14, 15)] arranged one on top of the other are bonded to one another in a laminating press by the influence of pressure and heat,

after removal of the plastic card body [(16)] from the laminating press, the recess [(12)] for the electronic component (chip module) [(11)] is milled into said body and

subsequently, the component [(11)] for establishing an electrical connection with the connecting areas [(2)] on the conductor track supporting layer [(1)] is inserted into the recess [(12)] of the plastic card body [(16)],

[characterized by] comprising

the making of indentations [(4a, 4b, 4c)] into the conductor track supporting layer [(1)] at predetermined locations for the placement of connecting areas [(3)],

the coating of the conductor track supporting layer [(1)] in an application method, preferably a screen printing method, with conductor tracks [(2)] and connecting areas [(3)] connected to the conductor tracks [(2) consisting of] comprising screen printing paste in such a way that the paste or high-viscosity liquid used for the coating fills the indentations [(4a, 4b, 4c)] in the conductor track layer [(1)], the milling-out of the recesses [(12)] for the electronic components [(11)] from the outer side of the plastic card body [(16)], which is remote from the side of the conductor track supporting layer [(1)] coated with conductor tracks, the recess [(12)] having such a depth that its bottom region reaches into the conductor track supporting layer (1) and the indentations [(4a, 4b, 4c)] filled with screen printing paste of the conductor track supporting layer [(1)] are exposed.

10. (Amended) The method as claimed in claim 9, [characterized in that] wherein the depressions [(4a, 4b, 4c)] are punched into the conductor track supporting layer [(1)] as through-holes [(6)].

11. (Amended) The method as claimed in claim 10, [characterized in that,] wherein after the punching-out of the holes [(6)], the conductor track supporting layer [(1)] is coated on one side with a protective film [(10)].

12. (Amended) The method as claimed in claim 9, [characterized in that] wherein a plurality of sublayers [(18, 19, 20)] provided with through-holes [(21)] are stacked exactly in position one on top of the other and bonded to one another to form a common conductor track supporting layer (1), indentations [(4a, 4b, 4c)] of different depths being formed by making the positions of the through-holes [(21)] in the sublayers [(18, 19, 20)] coincide.